



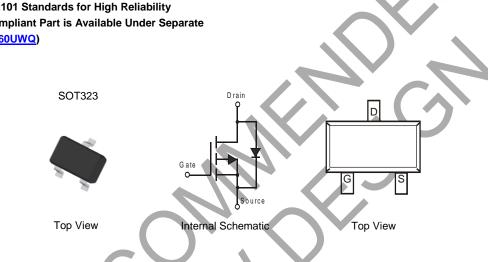
P-CHANNEL ENHANCEMENT MODE MOSFET

Features

- Low On-Resistance •
- $100m\Omega @ V_{GS} = -4.5V$
- $120m\Omega @ V_{GS} = -2.5V$
- $160m\Omega @ V_{GS} = -1.8V$
- Very Low Gate Threshold Voltage V_{GS(TH)} ≤ 1V
- Low Input Capacitance
- Fast Switching Speed
- Low Input/Output Leakage
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability
- An Automotive-Compliant Part is Available Under Separate Datasheet (DMP2160UWQ)

Mechanical Data

- Case: SOT323 •
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020D
- Terminals Connections: See Diagram Below
- Terminals: Finish Matte Tin Annealed over Alloy 42 Leadframe. Solderable per MIL-STD-202, Method 208 @3
- Weight: 0.006 grams (Approximate)



Ordering Information (Note 4)

	Part Number	Compliance	Case	Packaging
	DMP2160UW-7	Standard	SOT323	3000/Tape & Reel
Notes:	1. No purposely added lead. F	ully EU Directive 2002/95/EC (RoHS), 2	011/65/EU (RoHS 2) & 2015/863/EU (RoHS	3) compliant.

1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant. 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.

3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

Marking Information

	DMF	ΥM
		\square

DMF = Marking Code YM = Date Code Marking Y = Year (ex: F = 2018)M = Month (ex: 9 = September)

Date Code Key												
Year	2018		2019	2020		2021	2022		2023	2024		2025
Code	F		G	Н			J		K	L		М
Month	Jan	Feb	Mar	Apr	Мау	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	0	N	D



Maximum Ratings ($@T_A = +25^{\circ}C$, unless otherwise specified.)

Characteristic		Symbol	Value	Unit
Drain-Source Voltage	V _{DSS}	-20	V	
Gate-Source Voltage		V _{GSS}	±12	V
Drain Current (Note 5)	T _A = +25°C T _A = +70°C	ID	-1.5 -1.2	А
Pulsed Drain Current		I _{DM}	-10	А

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Total Power Dissipation (Note 5)	PD	350	mW
Thermal Resistance, Junction to Ambient	R _{θJA}	360	°C/W
Operating and Storage Temperature Range	TJ, TSTG	-55 to +150	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

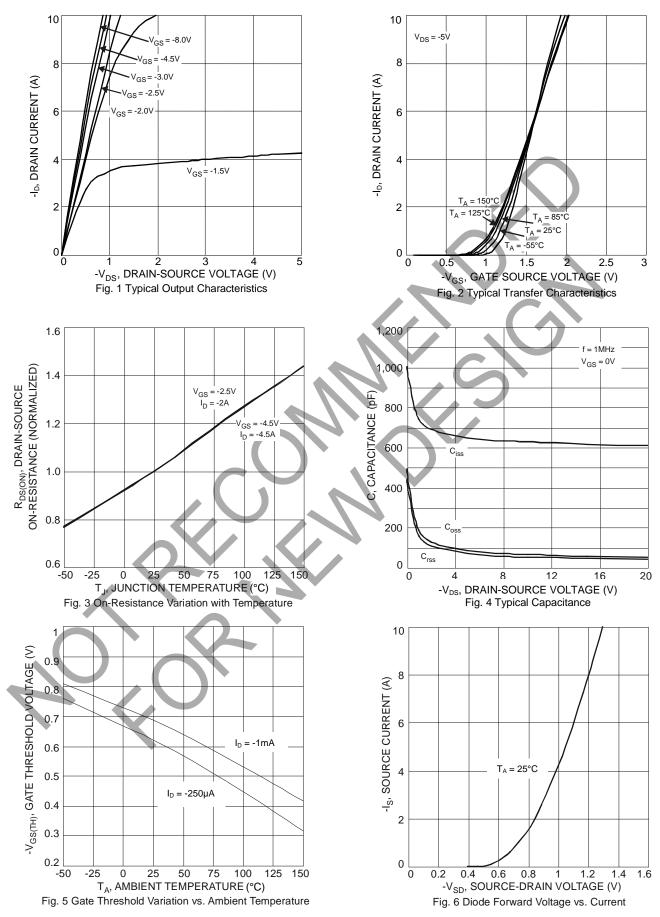
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 6)						
Drain-Source Breakdown Voltage	BV _{DSS}	-20	—		V	$V_{GS} = 0V, I_D = -250\mu A$
Zero Gate Voltage Drain Current $T_J = +2$	5°C I _{DSS}		_	-1.0	μA	V_{DS} = -20V, V_{GS} = 0V
Gate-Source Leakage	I _{GSS}	-		±100 ±800	nA	$V_{GS} = \pm 8V, V_{DS} = 0V$ $V_{GS} = \pm 12V, V_{DS} = 0V$
ON CHARACTERISTICS (Note 6)					•	•
Gate Threshold Voltage	V _{GS(TH)}	-0.4	-0.6	-0.9	V	$V_{DS} = V_{GS}, I_D = -250 \mu A$
Static Drain-Source On-Resistance	Rds(on)		75 90 120	100 120 160	mΩ	V _{GS} = -4.5V, I _D = -1.5A V _{GS} = -2.5V, I _D = -1.2A
Forward Transconductance		+	4	-	S	V _{GS} = -1.8V, I _D = -1A V _{DS} = -10V, I _D = -1.5A
Diode Forward Voltage (Note 6)	V _{SD}	_	_	-1.0	V	$V_{GS} = 0V, I_{S} = -1.0A$
DYNAMIC CHARACTERISTICS						
Input Capacitance	C _{iss}	_	627		pF	
Output Capacitance	Coss	_	64		pF	$V_{DS} = -10V, V_{GS} = 0V$ f = 1.0MHz
Reverse Transfer Capacitance	C _{rss}	_	53		pF	

Notes: 5. Device mounted on 1inch² FR-4 PCB with 2 oz. Copper. $t \le 10$ sec. 6. Short duration pulse test used to minimize self-heating effect.



NOT RECOMMENDED FOR NEW DESIGN USE <u>DMP2165UW</u>

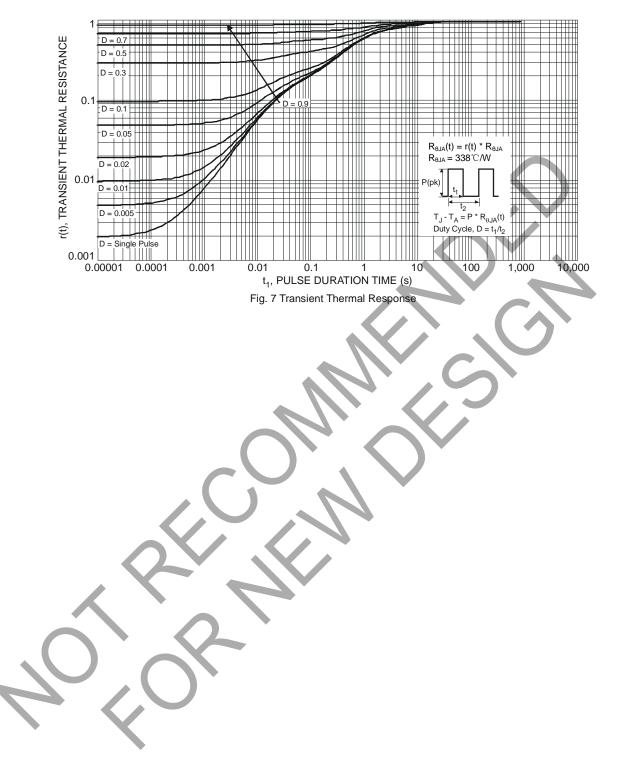
DMP2160UW





NOT RECOMMENDED FOR NEW DESIGN USE <u>DMP2165UW</u>

DMP2160UW

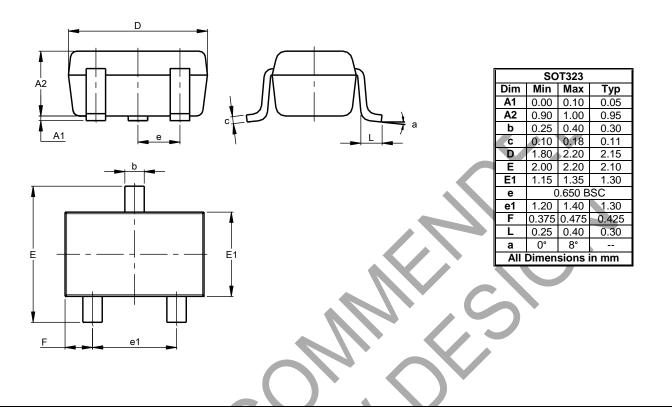




Package Outline Dimensions

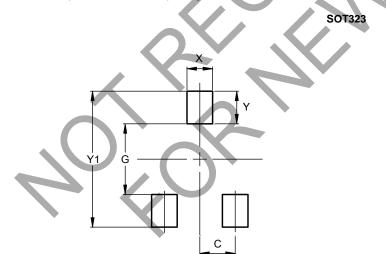
Please see http://www.diodes.com/package-outlines.html for the latest version.

SOT323



Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.



Dimensions	Value (in mm)			
С	0.650			
G	1.300			
Х	0.470			
Y	0.600			
Y1	2.500			



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